

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	366	257/e21.626.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/10 23:56
L2	452	257/e21.64.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/11 00:00
L4	79	(257/e21.176-e21.186).ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/10 23:59
L5	1	257/e21.374.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/11 00:00
L6	3	257/e21.458.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/11 00:00
S1	3292	438/275,257,211,216,219,221,248, 272,279,287,294,295,286,359.ccls. and @ad<="20001207"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/10 23:56
S2	1112	438/275,257,211,216,219,221,248, 272,279,287,294,295,286,359.ccls. and @ad<="20001207" and spacers	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:12

## EAST Search History

S3	1258	438/106,112,121,124,125,126,127. ccls. and @ad<="20050208" and (die or chip) and mount\$3 and (underfill\$3 or encapsulant or encapsulating or resin) and (heat\$3 or temperature or anneal\$3) and (curing or cured)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:16
S4	972	438/106,112,121,124,125,126,127. ccls. and @ad<="20050208" and (die or chip) and mount\$3 and (underfill\$3 or encapsulant or encapsulating or resin) and (heat\$3 or temperature or anneal\$3) and (curing or cured) and expos\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:16
S5	584	438/106,112,121,124,125,126,127. ccls. and @ad<="20050208" and (die or chip) and mount\$3 and (underfill\$3 or encapsulant or encapsulating or resin) and (heat\$3 or temperature or anneal\$3) and (curing or cured) and expos\$3 and external	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:17
S6	58	438/106,112,121,124,125,126,127. ccls. and @ad<="20050208" and (die or chip) and mount\$3 and (underfill\$3 or encapsulant or encapsulating or resin) and (heat\$3 or temperature or anneal\$3) and (curing or cured) and expos\$3 and external and housing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:18
S7	175	"438"/\$.ccls. and @ad<="20050208" and (die or chip) and mount\$3 and (underfill\$3 or encapsulant or encapsulating or resin) and (heat\$3 or temperature or anneal\$3) and (curing or cured) and expos\$3 and external and housing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:18
S8	491	"257"/\$.ccls. and @ad<="20050208" and (die or chip) and mount\$3 and (underfill\$3 or encapsulant or encapsulating or resin) and (heat\$3 or temperature or anneal\$3) and (curing or cured) and expos\$3 and external and housing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/30 10:26
S9	1	11/281502	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/10 09:44

## EAST Search History

S10	22	"438"/\$.ccls. and @ad<="20011004" and (spacers near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/06 08:53
S11	39	"257"/\$.ccls. and @ad<="20011004" and (spacers near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:17
S12	1	"257"/\$.ccls. and @ad<="20011004" and (spacers near interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:15
S13	1	"438"/\$.ccls. and @ad<="20011004" and (spacers near interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:15
S14	1	semiconductor and @ad<="20011004" and (spacers near interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:16
S15	39	"257"/\$.ccls. and @ad<="20011004" and (spacers near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:15
S16	48	semiconductor and @ad<="20011004" and (spacers near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:18

## EAST Search History

S17	281	"438"/\$.ccls. and @ad<="20011004" and (spacers with interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 14:03
S18	50	"438"/\$.ccls. and @ad<="20011004" and (sidewall near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:20
S19	71	"257"/\$.ccls. and @ad<="20011004" and (sidewall near interface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 13:19
S20	31	"438"/\$.ccls. and @ad<="20011004" and (spacers with interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 14:04
S21	34	"257"/\$.ccls. and @ad<="20011004" and (spacers with interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 14:04
S22	35	semiconductor and @ad<="20011004" and (spacers with interface) and polycide	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/31 14:04
S23	1	10/008700	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/07/06 08:53

## EAST Search History

S24	1	10/008700	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/10 09:45
S25	0	257/e21.3205.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/10 09:45
S26	0	257/e21.4763.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/10 09:45
S27	1785	(438/778).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/10 09:46
S28	133	(438/764).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/10 09:46
S29	1008	(438/595).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/10 09:46
S30	649	(438/782).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/10 09:46

## EAST Search History

S31	988	(438/787).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/10 09:47
S32	218	438/778,764,595,782,787.ccls. and gate and ((dielectric or oxide or insulat\$4) with (surround\$4 or protect\$4)) and (plug or contact) and expos\$3 and @ad<="20001207"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/10 09:49